



## Material Content Data Sheet



<b>Sales Product Name</b>		IGW60T120		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000920000						
<b>Package</b>		PG-TO247-3-21		<b>Weight*</b>		6001.89 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	15.927	0.27	0.27	2654	2654
leadframe	non noble metal	iron	7439-89-6	3.972	0.07		662	
	inorganic material	phosphorus	7723-14-0	1.192	0.02		199	
	non noble metal	copper	7440-50-8	3967.074	66.11	66.20	660970	661831
wire	non noble metal	aluminium	7429-90-5	13.501	0.22	0.22	2250	2250
encapsulation	organic material	carbon black	1333-86-4	21.244	0.35		3540	
	inorganic material	antimonytrioxide	1309-64-4	44.419	0.74		7401	
	plastics	brominated resin	-	50.213	0.84		8366	
	plastics	epoxy resin	-	366.941	6.11		61137	
	inorganic material	silicondioxide	60676-86-0	1448.452	24.13	32.17	241332	321776
leadfinish	non noble metal	tin	7440-31-5	31.874	0.53	0.53	5311	5311
plating	non noble metal	nickel	7440-02-0	29.065	0.48	0.48	4843	4843
solder	non noble metal	antimony	7440-36-0	0.801	0.01		133	
	noble metal	silver	7440-22-4	2.003	0.03		334	
	non noble metal	tin	7440-31-5	5.208	0.09	0.13	868	1335
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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